

TECHNICAL BULLETIN

Epoxy/Anhydride
Potting Compound
\$\$1948

Description

EPMAR SS1948 is a two component, filled epoxy potting compound. It is a heat cure epoxy developed for electronic applications such as impregnation of electronic components. The cured material exhibits low foam formation and very good capillary flow properties.

Typical Uncured Properties:

	Part A	Part B	Mixed
Color	Tan	Amber	Tan
Specific gravity	1.77+/- 0.10	1.06 +/- 0.10	1.63 +/- 0.20
Viscosity @ 25°C, cps	350,000 - 550,000	640-680	3800-5300
Filler content, %	66	0	47

Note: Values not intended for use in specification preparation

Handling and Basic Properties:

Mix Ratio	100:40 parts by weight 4:1 parts by volume
Glass transition temperature,°C	60
Cure Schedule	10 min. @ 230°C Post cure 3 hours @ 150°C
Hardness, Shore D	70

Storage

Product should be stored at 60°F-90°F for best performance. Shelf life for this product is 1 year under recommended storage conditions and if drum remains sealed.

Disclaimer

The above information is based on preliminary laboratory tests and believed to be accurate. All properties shown are typical values and are not intended to be used in the preparation of specifications. While the information presented herein is believed to be reliable and represent the best available data on this (or these products), no guarantee, warranty, or representation is made, intended or implied as to the correctness or sufficiency of any information or as to the suitability of any chemical compound for any particular use. It is recommended that each user conduct a sufficient investigation to establish the suitability of product application in any particular use.

Contact us for any additional application information.

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